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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: West et al. Docket No.: TI-36238
Serial No.: 10/697,137 Examiner: Guerrero, M.
Filing Date: 10/30/2003 Art Unit: 2822
Customer No.: 23494 Conf. No.: 9756
Title: METHOD FOR IMPROVING RELIABILITY OF COPPER INTERCONNECTS

TRANSMITTAL OF FORMAL DRAWINGS

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

Attn: Official Draftsperson

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner of Patents, P. O. Box 1450, Alexandria, VA 22313-1450.

Date

12-2-05
Marianna Smith
Marianna Smith

Submitted herewith are three (3) sheets of formal drawings.

Charge any necessary fee to Deposit Account No. 20-0668. The original and a copy of this authorization are enclosed.

Respectfully submitted,

Jacqueline J. Garner
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